

UNISONIC TECHNOLOGIES CO., LTD

16N50 **Power MOSFET**

16 A, 500 V N-CHANNEL POWER MOSFET

DESCRIPTION

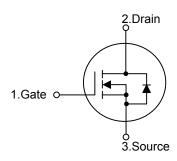
The UTC 16N50 is an N-channel mode power MOSFET using UTC's advanced technology to provide customers with planar stripe and DMOS technology. This technology allows a minimum on-state resistance and superior switching performance. It also can withstand high energy pulse in the avalanche and commutation mode.

The UTC 16N50 is generally applied in high efficiency switch mode power supplies, active power factor correction and electronic lamp ballasts based on half bridge topology.

FEATURES

- * $R_{DS(ON)}$ < 0.38 Ω @ V_{GS} =10V, I_{D} =8A
- * High Switching Speed
- * 100% Avalanche Tested

SYMBOL

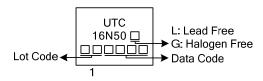


ORDERING INFORMATION

	Ordering	Dooksons	Pin Assignment			Daakina		
	Lead Free	Halogen Free	Package	1	2	3	Packing	
	16N50L-TF1-T	16N50G-TF1-T	TO-220F1	G	D	S	Tube	
	16N50L-TF2-T	16N50G-TF2-T	TO-220F2	G	D	S	Tube	
Note:	Pin Assignment: G: G	ate D: Drain S: Source					_	

16N50L-TF1-T (1)Packing Type (1) T: Tube (2)Package Type (2) TF1: TO-220F1, TF2: TO-220F2 (3) L: Lead Free, G: Halogen Free and Lead Free (3)Green Package

MARKING



TO-220F1 TO-220F2

www.unisonic.com.tw 1 of 6 16N50

■ **ABSOLUTE MAXIMUM RATINGS** (T_C=25°C, unless otherwise specified)

PARAME	ΓER	SYMBOL	RATINGS	UNIT	
Drain-Source Voltage		V_{DSS}	500	V	
Gate-Source Voltage		V_{GSS}	±30	V	
Danie Current	Continuous (T _C =25°C)	I _D 16 (Note 2)		Α	
Drain Current	Pulsed (Note 3)	I _{DM} 64 (Note 2)		Α	
Avalanche Energy	valanche Energy Single Pulsed (Note 4)		780	mJ	
Peak Diode Recovery dv/dt (Not	e 5)	dv/dt	4.5	V/ns	
Device Dissipation (T. –25°C)	TO-220F1		52	W/°C	
Power Dissipation (T _C =25°C)	TO-220F2	Б	62		
Linear Derating Factor above	TO-220F1	P_D	0.41		
T _C =25°C	TO-220F2		0.31		
Junction Temperature		T_J	+150	°C	
Storage Temperature		T _{STG}	-55~+150	°C	

Notes: 1. Absolute maximum ratings are those values beyond which the device could be permanently damaged.

Absolute maximum ratings are stress ratings only and functional device operation is not implied.

- 2. Drain current limited by maximum junction temperature
- 3. Repetitive Rating: Pulse width limited by maximum junction temperature
- 4. L = 6.1mH, I_{AS} = 16A, V_{DD} = 50V, R_{G} = 25 Ω , Starting T_{J} = 25 $^{\circ}$ C
- 5. $I_{SD} \le 16A$, di/dt $\le 200A/\mu s$, $V_{DD} \le BV_{DSS}$, Starting $T_J = 25^{\circ}C$

■ THERMAL DATA

PAF	RAMETER	SYMBOL	RATINGS	UNIT	
Junction to Ambient		θ_{JA}	62.5	°C/W	
lunation to Occa	TO-220F1	0	2.4	°C/W	
Junction to Case	TO-220F2	θυς	2.0		

■ ELECTRICAL CHARACTERISTICS (T_C=25°C, unless otherwise specified)

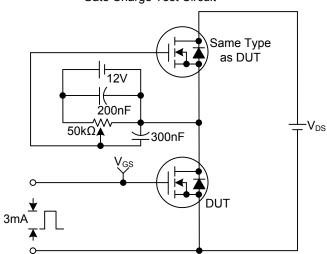
PARAMETER		SYMBOL	TEST CONDITIONS	MIN	TYP	MAX	UNIT	
OFF CHARACTERISTICS								
Drain-Source Breakdown Voltage	Э	BV_{DSS}	$I_D = 250 \mu A, V_{GS} = 0 V$	500			V	
Drain-Source Leakage Current		I _{DSS}	V _{DS} =500V, V _{GS} =0V			1	μΑ	
			V _{DS} =400V, V _{GS} =0V, T _C =125°C			10	μA	
Cata Cauraa Laakaga Currant	Forward	1	V_{GS} =+30V, V_{DS} =0V			+100	nΑ	
Gate- Source Leakage Current	Reverse	I _{GSS}	V_{GS} =-30V, V_{DS} =0V			-100	nΑ	
ON CHARACTERISTICS								
Gate Threshold Voltage		$V_{GS(TH)}$	$V_{DS}=V_{GS}$, $I_D=250\mu A$	2.0		4.0	V	
Static Drain-Source On-State Re	sistance	R _{DS(ON)}	V_{GS} =10V, I_D =8A		0.31	0.38	Ω	
DYNAMIC PARAMETERS								
Input Capacitance		C_{ISS}			1100	1945	pF	
Output Capacitance		Coss	V _{GS} =0V, V _{DS} =25V, f=1.0MHz		235	310	pF	
Reverse Transfer Capacitance		C_{RSS}			25	30	pF	
SWITCHING PARAMETERS								
Total Gate Charge		Q_{G}	V _{GS} =10V, V _{DS} =50V, I _D =1.3A (Note 1, 2)		32	45	nC	
Gate to Source Charge		Q_{GS}			8.5		nC	
Gate to Drain Charge		Q_{GD}			14		nC	
Turn-ON Delay Time		$t_{D(ON)}$			70	90	ns	
Rise Time		t_R	V _{DD} =30V, I _D =0.5A, R _G =25Ω (Note 1, 2)		200	310	ns	
Turn-OFF Delay Time		$t_{D(OFF)}$			750	900	ns	
Fall-Time		t_{F}			380	500	ns	
SOURCE- DRAIN DIODE RATINGS AND CHARACTERISTICS								
Maximum Body-Diode Continuou	is Current	Is				16	Α	
Maximum Body-Diode Pulsed Cu	ırrent	I _{SM}				64	Α	
Drain-Source Diode Forward Vol	tage	V_{SD}	I _S =16A, V _{GS} =0V			1.4	V	

Notes: 1. Pulse Test: Pulse width ≤ 300µs, Duty cycle ≤ 2%

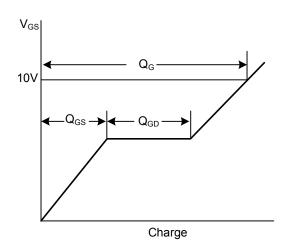
^{2.} Essentially independent of operating temperature

■ TEST CIRCUITS AND WAVEFORMS

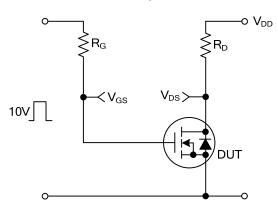
Gate Charge Test Circuit



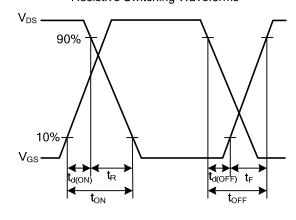
Gate Charge Waveforms



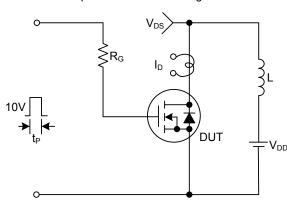
Resistive Switching Test Circuit



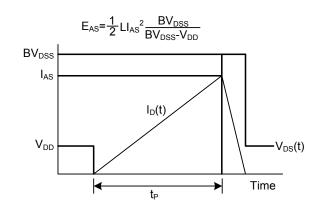
Resistive Switching Waveforms



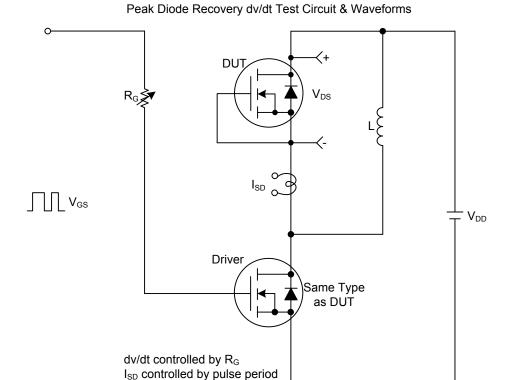
Unclamped Inductive Switching Test Circuit

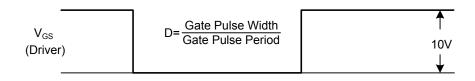


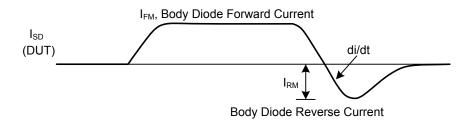
Unclamped Inductive Switching Waveforms

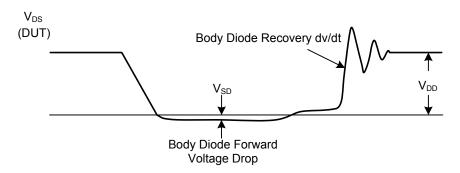


■ TEST CIRCUITS AND WAVEFORMS(Cont.)

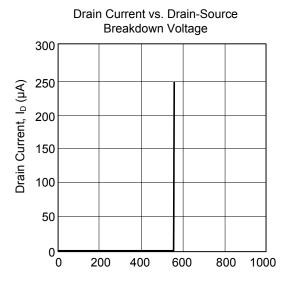




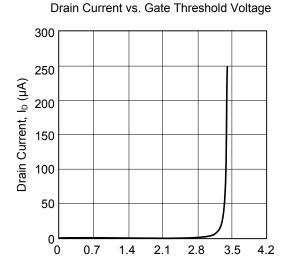




■ TYPICAL CHARACTERISTICS

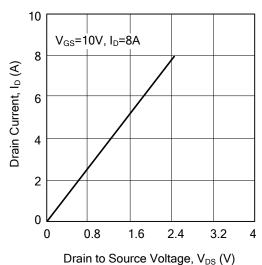


Drain-Source Breakdown Voltage, BV_{DSS} (V)

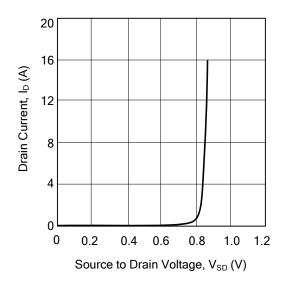


Gate Threshold Voltage, V_{TH} (V)





Drain Current vs. Source to Drain Voltage



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